PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tomohiro UNO	05/26/2010
Keiichi KIMURA	05/26/2010
Takashi YAMADA	05/26/2010

RECEIVING PARTY DATA

Name:	NIPPON STEEL MATERIALS CO., LTD.
Street Address:	14-1, Sotokanda 4-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1010021

Name:	NIPPON MICROMETAL CORPORATION
Street Address:	158-1, Oaza Sayamagahara, Iruma-shi
City:	Saitama
State/Country:	JAPAN
Postal Code:	3580032

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12747434

CORRESPONDENCE DATA

Fax Number: (202)756-8087
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
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Address Line 2: 600 13TH STREET, N.W.

CH $40.00 12747434

Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20005-3096
ATTORNEY DOCKET NUMBER:	086039-0081
NAME OF SUBMITTER:	Hiroko Lavietes

Total Attachments: 3
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RECORDATION FORM COVER SHEET

Docket No.: 086039-0081 **PATENTS ONLY**

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)

Tomohiro UNO; Keiichi KIMURA; Takashi YAMADA

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: **NIPPON STEEL MATERIALS CO., LTD.**
Address: **14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1010021 Japan**

Name: **NIPPON MICROMETAL CORPORATION**
Address: **158-1, Oaza Sayamagahara, Iruma-shi, Saitama 3580032 Japan**

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): **May 26, 2010**

☒ Assignment
☐ Merger
☐ Security Agreement
☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

4. Application or patent number(s):

☒ This document is being filed together with a new application.

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP
Internal Address:
Street Address: 600 13th Street, N.W.
City: Washington State: D. C. Zip: 20005-3096
Phone Number: 212.547.5400
Fax Number: 202.756.8087
Email Address:

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) $40.00

☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information:

a. Credit Card Last 4 Numbers ________
Expiration Date ________

b. Deposit Account Number 500417
Authorized User Name ________

9. Signature.

Louis J. DelJuidice, 47,522 June 10, 2010

Name and Registration No. of Person Signing | Signature | Date

Total number of pages including cover sheet, attachments and documents: 3

ASSIGNMENT

For value received, I /we Tomohiro UNO, Keiichi KIMURA, and Takashi YAMADA

residing respectively at Tokyo, Japan; Tokyo, Japan; Saitama, Japan

hereby sell, assign, and transfer to NIPPON STEEL MATERIALS CO., LTD.; NIPPON MICROMETAL CORPORATION

corporations existing under the laws of Japan

located at 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1010021, Japan; 158-1, Oaza Sayamagahara, Iruma-shi, Saitama 3580032, Japan

and its successors, assigns, and legal representatives, the entire right, title, and interest for all countries including the United States of America, in and to certain inventions relating to BONDING WIRE FOR SEMICONDUCTOR DEVICE

described in an application for Letters Patent of the United States, executed by me/us on this date, and all patents which may be granted therefor, and all divisions, reissues, continuations and extensions thereof, and authorize and request the Commissioner of Patents and Trademarks to issue all patents on said improvements or resulting therefrom to said Company as assignee of the entire interest, and covenant that I/we have full right so to do, and agree that I/we will communicate to said Company or its representatives any facts known to me/us respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said Company, its successors, assigns, and nominees, to obtain and enforce proper protection for said invention in the United States.

Signature *Tomohiro Uno* Date *May 26, 2010*
Tomohiro UNO

Signature *Keiichi Kimura* Date *May 26, 2010*
Keiichi KIMURA

Signature ______________ Date ______________
Takashi YAMADA

Signature ______________ Date ______________

Signature ______________ Date ______________

Signature ______________ Date ______________

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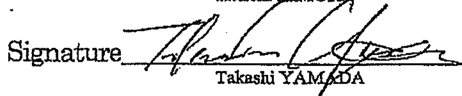
and its successors, assigns, and legal representatives, the entire right, title, and interest for all countries including the United States of America, in and to certain inventions relating to BONDING WIRE FOR SEMICONDUCTOR DEVICE

described in an application for Letters Patent of the United States, executed by me/us on this date, and all patents which may be granted therefor, and all divisions, reissues, continuations and extensions thereof, and authorize and request the Commissioner of Patents and Trademarks to issue all patents on said improvements or resulting therefrom to said Company as assignee of the entire interest, and covenant that I/we have full right so to do, and agree that I/we will communicate to said Company or its representatives any facts known to me/us respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said Company, its successors, assigns, and nominees, to obtain and enforce proper protection for said invention in the United States.

Signature__________ Date__________
Tomohiro UNO

Signature__________ Date__________
Keiichi KIMURA

Signature  Date May 26, 2010
Takashi YAMADA

Signature__________ Date__________

Signature__________ Date__________

Signature__________ Date__________